imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

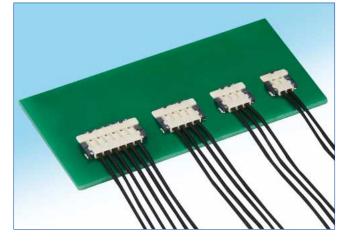
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NEW

Small-Sized, Low Profile 1.0mm Height, Wire-to-Board Connectors for Power Supply

DF58 Series



Features

1. Small-sized, low profile connector

Low profile design of 1.0mm stacking height, the connector is suitable for small-sized devices.

2. Leveling of the vertical mating cable

Vertical insertion of the connector for mating enhances the assembly operation within device.

3. Proprietary ViSe Lock design

The cable side lock has been strengthened with our proprietary ViSe Lock mechanism*, preventing the cables from being easily disconnected due to tough routing or an excessive load. (*ViSe Lock: Vertical-insertion Swing-extraction)(Fig.2)*Patent pending

4. High current capability up the maximum of 3.0A (2pos. : When 28AWG is used)

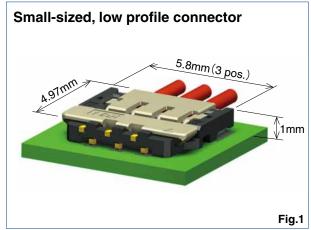
By adopting high conductivity material and lowering contact resistance through optimized contact force, high-current capability is achieved in spite of its small size.

5. Highly reliable contact design

Effective mating length of 0.29mm is achieved in spite of low profile 1.0mm stacking height. The 2-point clipping contact stabilizes contact resistance.

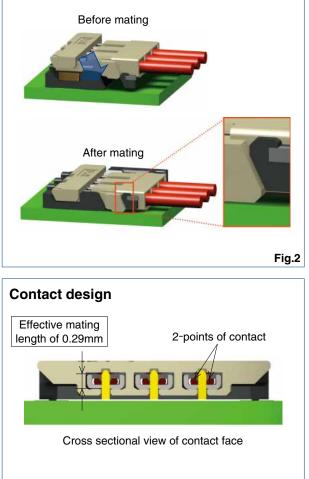
6. Halogen-free*

*As defined by IEC 61249-2-21 Br-900ppm max, Cl-900ppm max, Br+Cl-1,500ppm max



Description of the ViSe Lock Design

Insertion operation appears to be vertical mating. However, it is actually inserted at an angle which ensures high retention force in upper direction.



Product Specifications

		omoution	<u> </u>						
			2pos.	3pos.	4pos.	6pos.	One watting temperature range 55° to 95° (Note 1)		
Rating	Current rati	ing 28AWG	3.0A	2.5A	2.0A 1.5A		Operating temperature range -55℃ to 85℃ (Note 1) Operating humidity range 20% to 80% (Note 2)		
		30AWG	2.5A	2.0A			Operating number value 20 % to 50 % (Note 2)		
	Voltage rat	ing	g 100V AC / DC				Storage temperature range -10°C to 60°C (Note 3) Storage humidity range 40% to 70% (Note 3)		
Ite	em	Specification					Conditions		
1.Insulati resistar	•••	100MΩ min.					100V DC		
2.Withsta voltage	nding	No flashover	or insulat	ion break	down	į	500V AC / 1 minute		
3.Contac resistar	-	10mΩ max.					20mV max. at 1mA.		
4.Vibration		No electrical discontinuity of 1μ s or longer No damage, cracks or parts dislocation.				er I	Frequency : 10 to 55Hz, single amplitude of 0.75mm, 10 cycles, 3 direction		
5.Shock		No electrical discontinuity of 1μ s or longer No damage, cracks or parts dislocation.					Acceleration of 490m/s ² , 11ms duration, sine half- wave, 3 cycles in each of the 3 axis		
6.Humidity		Contact resistance : $20m\Omega$ max., Insulation resistance : $100M\Omega$ min. No damage, cracks or parts dislocation.				(96 hours at 40 \pm 2°C, and humidity of 90 to 95%		
7.Temperature cycle		Contact resistance : 20mΩ max., Insulation resistance : 100MΩ min. No damage, cracks or parts dislocation.					-55° C → 5 to 35° C → 85 $^{\circ}$ C → 5 to 35° C Times : 30 min. → 2 min. to 3 min. → 30 min. → 2 min. to 3 min. 5 cycles		
8.Durability		Contact resistance : $20m\Omega$ max., No damage, cracks or parts dislocation.					10 cycles		
		No deformation of components affecting performance					Reflow : See recommended temperature profile (Page 6) Manual soldering : 350°C for 3 seconds		
Note 1 Line	ludes tomo	oraturo riso cau	and by a	orating	urront				

Note 1 : Includes temperature rise caused by operating current.

Note 2 : Use in environments without condensation.

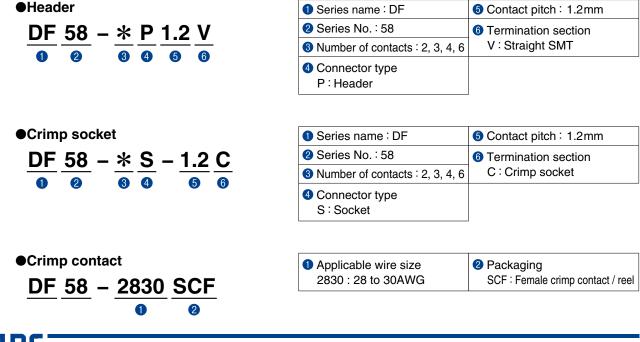
Note 3 : The term "storage" refers to products stored for a long period prior to soldering or usage. The operating temperature and humidity range covers the non-conducting condition of installed connectors in storage, shipment or during transportation.

Materials / Finish

Product	Part	Material	Finish	Remarks
Header	Insulator LCP		Black	UL94V-0
neauer	Contacts	Copper Alloy	Tin Plated	
Crimp socket	Insulator	LCP	Natural	UL94V-0
Crimp contacts	Contacts	Copper Alloy	Tin Plated	

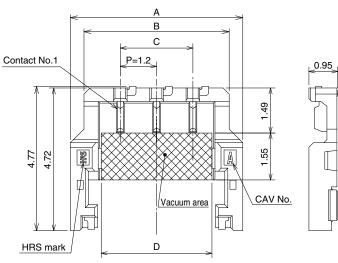
Product Number Structure

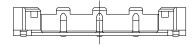
Refer to the chart below when determining the product specifications from the product number. Please select from the product numbers listed in this catalog when placing orders.



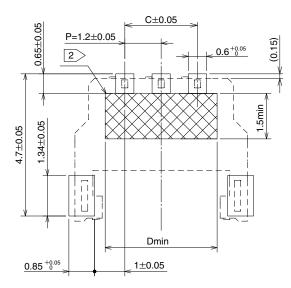
Header (SMT)







Recommended PCB layout



[Specification number]

(21) : Tin plated, Embossed tape packaging (6,000pcs/reel)

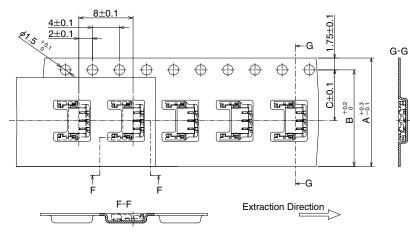
Unit : mm

Part No.	HRS No.	No. of contacts	А	В	С	D
DF58-2P-1.2V(21)	666-1001-0 21	2	4.5	3.6	1.2	2.5
DF58-3P-1.2V(21)	666-1002-0 21	3	5.7	4.8	2.4	3.7
DF58-4P-1.2V(21)	666-1003-0 21	4	6.9	6.0	3.6	4.9
DF58-6P-1.2V(21)	666-1005-0 21	6	9.3	8.4	6.0	7.3

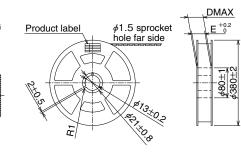
Note 1 : Embossed tape reel packaging (6,000pcs/reel).

Note $\boxed{2}$: The crossed-hatched area is a no conductive trace area.

Packaging Specification



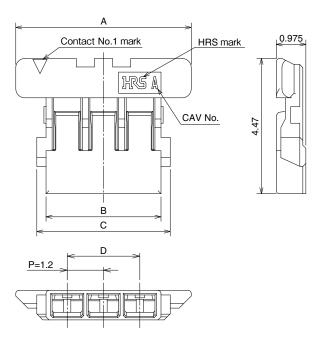




					Unit : mm
Part No.	A	В	С	D	E
DF58-2P-1.2V(21)	10	14.05	7 5	22.4	16.4
DF58-3P-1.2V(21)	16	14.25	7.5	22.4	16.4
DF58-4P-1.2V(21)	04	22.25	11.5	30.4	24.4
DF58-6P-1.2V(21)	24				24.4

Crimp socket

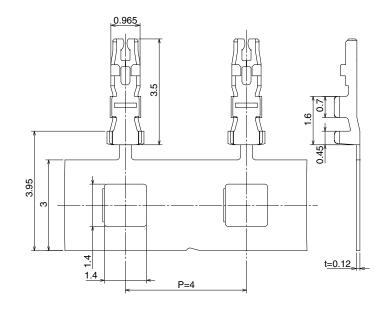




						Unit : mm
Part No.	HRS No.	No. of contacts	А	В	С	D
DF58-2S-1.2C	666-1006-0 00	2	4.6	2.6	3.21	1.2
DF58-3S-1.2C	666-1007-0 00	3	5.8	3.8	4.41	2.4
DF58-4S-1.2C	666-1008-0 00	4	7.0	5.0	5.61	3.6
DF58-6S-1.2C	666-1010-0 00	6	9.4	7.4	8.01	6.0

Note 1 : Please order by number of packing (1,000pcs/packing).

Crimp contact



Unit:mm HRS No. Part No. Packaging Quantity Finish DF58-2830SCF 666-1011-0 00 Reel 40,000 Tin plated

Note : This product is delivered in 40,000 pieces per reels. Please place orders in multiples of 40,000 pieces.

•Applicable wire (Tin plated annealed copper wire)

Unit : mm

		/		
Wire size (Stranded wire conductor)	Jacket outer diameter	Recommended cable	Strip length	
28AWG(7 / ¢0.127mm)				
30AWG(7/¢0.102mm)	∕¢0.5 to 0.6mm	UL1571 (Thin wire)	1.0 to 1.4mm	
$30AVVG(7 \neq 0.10211111)$				

Note 1 : When using other than the recommended wire, contact your nearest Hirose sales representative.

Note 2 : The strip length is a reference value. Please make adjustments so finished crimps will meet the specified values. Refer to the crimping quality standards (ATAD-H0848-00) for details.

Tools

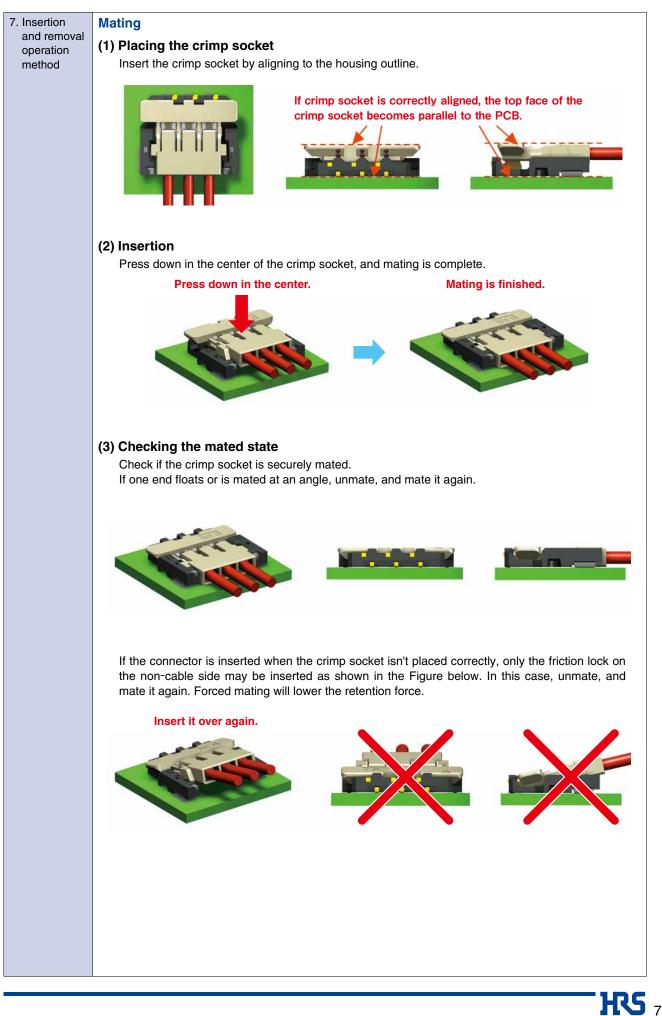
Unit : mm Туре Part No. HRS No. Applicable contact Applicator AP105-DF58-2830S 901-4649-0 00 Press CM-105C 901-0001-0 00 DF58-2830SCF HT307/DF58-2830HC Hand crimping tool Under development DF-C-PO(B) 550-0179-2 00 Contact extraction tool

Note : If any trouble has occurred due to tools other than the designated tool, Hirose bears no respoisibility for any trouble.

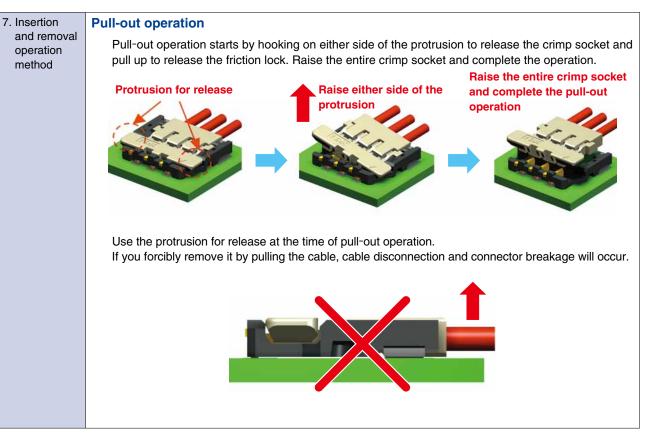
Operating Precautions

1. Recommended Temperature Profile (Lead-free soldering possible) 200							
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handling precautions at the time of insertion and extraction.		-					
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● Usage Recommendation



Recommended Usage





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